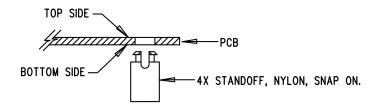


REVISION HISTORY						
EC0	REV	DESCRIPTION	APP. ENG.	DATE		
_	1	2ND PROTOTYPE	JON M.	06-15-15		

## NOTES: UNLESS OTHERWISE SPECIFIED

- 1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
- ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
- 3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
- 4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
- 5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
- DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
- 7. INSTALL 4 STANDOFFS AT 4 LOCATIONS AS SHOWN BELOW:



APPR	ROVALS	LINEAR MILPITAS PH: (40)	CCARTHY S, CA 950 8)432-19	5035 900
PCB DES.	AK	TECHNOLOGY LTC COL	néar.cor NFIDENTIA STOMER L	Ë-
APP ENG.	JON M.	TITLE: TOP ASSEMBLY DRAWING isoSPI 12-CELL BATTERY-STACK MONITOR		
		SIZE IC NO. LTC6811IG-1		REV.
		N/A DEMO CIRCUIT 2259A		2
SCALE = NONE		FILENAME: DC2259A-2.PCB	SHT 1	0F 2